

3A Ultra-small Load Switch with Slew Rate Control

Features

- Integrated P-channel MOSFET load switch
- Input voltage: 1.2V to 5.5V
- 3A maximum continuous switch current
- Switch on-resistance(typ.):
Rdson=24mΩ at VIN=5.5V
Rdson=29mΩ at VIN=3.3V
Rdson=73mΩ at VIN=1.2V
- Controlled slew rate to limit inrush currents
- Ultra low shutdown current
- Internal EN pull-down resistor
- WLCSP 1.355mm×0.855mm×0.55mm-6B

General Description

The AW35132 is a load switch with output slew rate control. The device integrates a 29mΩ (typ.) P-channel MOSFET, which can operate over a wide input range of 1.2V to 5.5V.

The AW35132 features output slew rate control, limiting inrush currents during turn-on to protect downstream devices.

Applications

Smart Wear

Vehicle Module

High-Definition Television(HDTV)

Typical Application Circuit

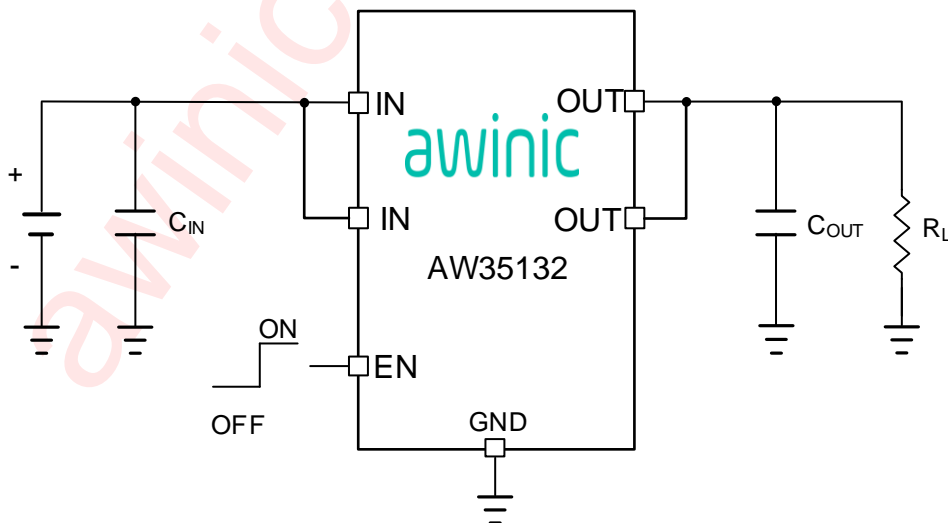


Figure 1 Typical Application circuit of AW35132

Pin Configuration And Top Mark

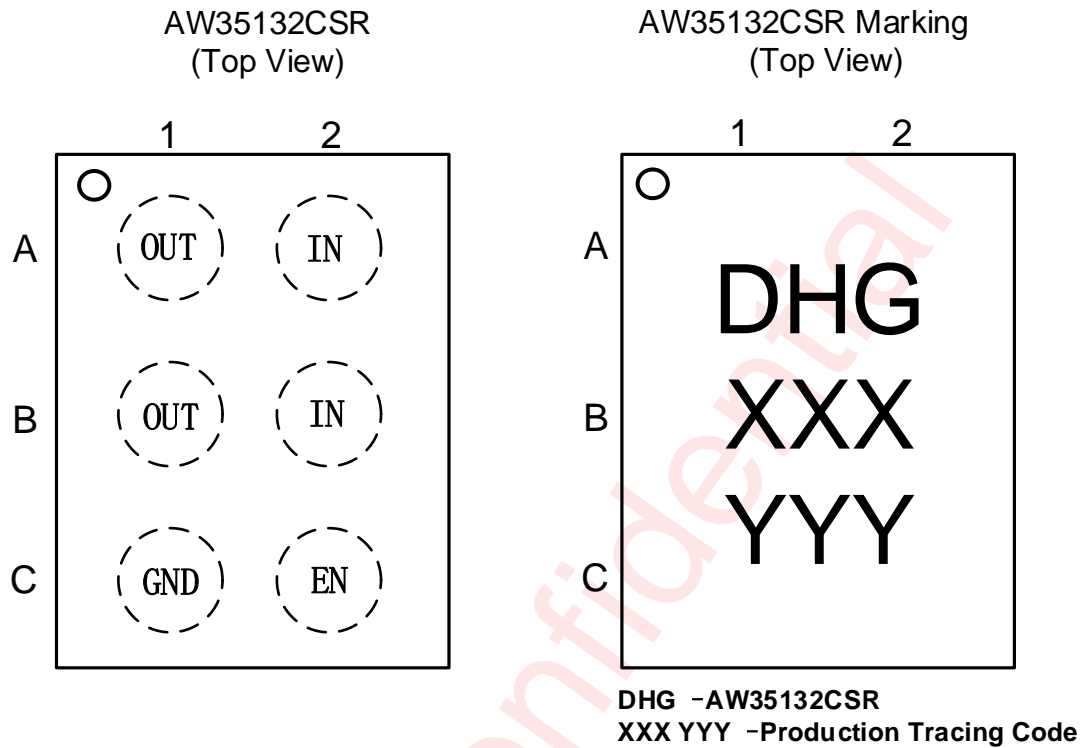


Figure 2 Pin Configuration and Top Mark

Pin Definition

Pin	Name	Description
A1	OUT	Switch output
B1		
C1	GND	Device ground
A2	IN	Switch input and power supply
B2		
C2	EN	Switch control input, active high

Functional Block Diagram

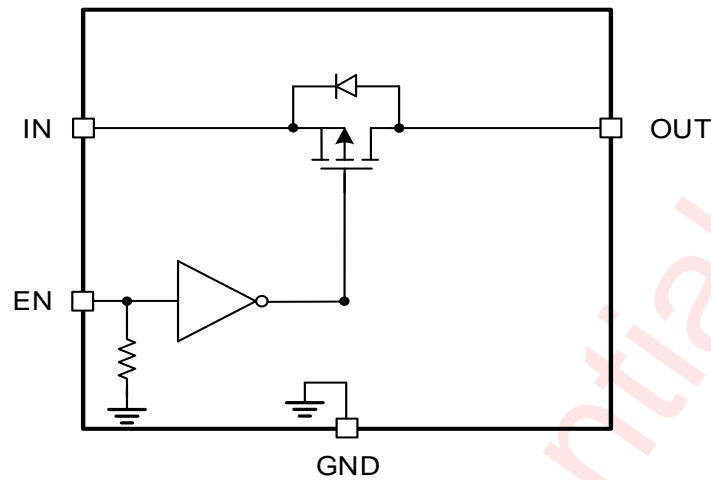


Figure 3 Functional Block Diagram

Typical Application Circuits

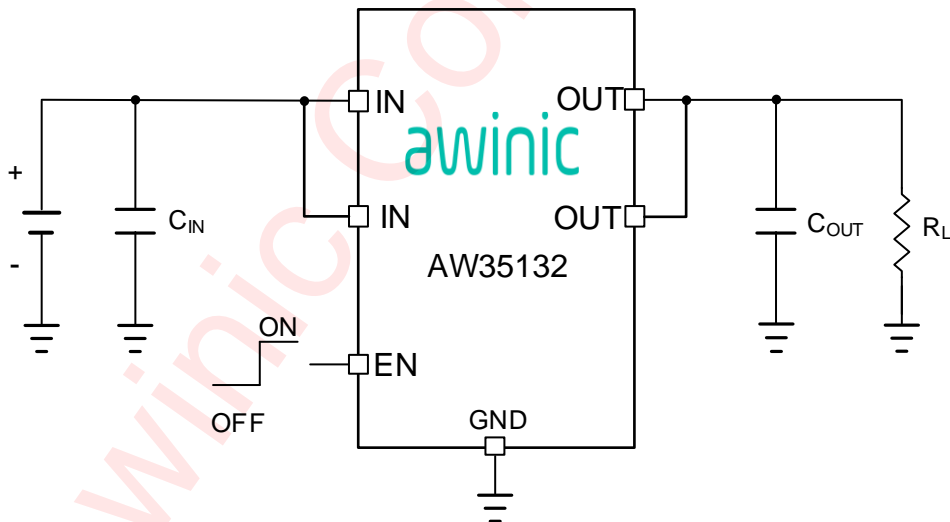


Figure 4 Typical Application circuit of AW35132

Ordering Information

Part Number	Temperature	Package	Marking	Moisture Sensitivity Level	Environmental Information	Delivery Form
AW35132CSR	-40°C~85°C	WLCSP 1.355mm×0.85 5mm×0.55mm -6B	DHG	MSL1	ROHS+HF	4500 units/ Tape and Reel

Absolute Maximum Ratings^(NOTE1)

PARAMETERS		RANGE
Supply Voltage Range V_{IN}		-0.3V to 6V
Enable Voltage Range	EN	-0.3V to 6V
Output Voltage Range	OUT	-0.3V to 6V
Maximum Continuous Switch Current for $V_{IN} \geq 1.5V$		3A
Maximum Continuous Switch Current for $1.2 \leq V_{IN} < 1.5V$ ^(NOTE 2)		2.5A
Maximum Peak Switch Current for $V_{IN} \geq 2.5V$ ^(NOTE 3)		4A
Junction-to-ambient Thermal Resistance θ_{JA} ^(NOTE 4)		100°C/W
Operating Free-air Temperature Range		-40°C to 85°C
Maximum Junction Temperature T_{JMAX}		150°C
Storage Temperature T_{STG}		-65°C to 150°C
Lead Temperature (Soldering 10 Seconds)		260°C
ESD		
HBM (Human Body Model) ^(NOTE 5)		±2kV
CDM (Charged Device Model) ^(NOTE 6)		±1.5kV
Latch-Up		
Latch-Up ^(NOTE 7)		+IT: 200mA -IT: -200mA

NOTE1: Conditions out of those ranges listed in "absolute maximum ratings" may cause permanent damages to the device. In spite of the limits above, functional operation conditions of the device should be within the ranges listed in "recommended operating conditions". Exposure to absolute-maximum-rated conditions for prolonged periods may affect device reliability.

NOTE2: The power mos enters saturation region, load capacity is reduced.

NOTE3: Limited by thermal design, and tested in 10ms width pulse current.

NOTE4: Thermal resistance from junction to ambient is highly dependent on PCB layout.

NOTE5: The human body model is a 100pF capacitor discharged through a 1.5kΩ resistor into each pin. Test method: ESDA/JEDEC JS-001-2017.

NOTE6: All pins. Test Condition: ESDA/JEDEC JS-002-2018.

NOTE7: Test Condition: JESD78E.

Recommended Operating Conditions

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{IN}	Input Voltage	1.2		5.5	V
V_{EN}	EN Voltage	0		5.5	V
V_{OUT}	Output Voltage	0		V_{IN}	V
C_{IN}	Input capacitance	0.1	1		μF
C_{OUT}	Output load capacitance	0.1	1		μF

Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise noted. Typical values are guaranteed for $V_{IN} = 3.3\text{V}$, $C_{IN} = 1\mu\text{F}$, $I_{IN} \leq 3\text{A}$.

PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT
INPUT CURRENTS						
I_Q	Input quiescent current	$V_{IN}=3.3\text{V}$, $V_{EN}=3.3\text{V}$, $I_{OUT}=0\text{A}$, $T_A=25^\circ\text{C}$		4	70	nA
		$V_{IN}=3.3\text{V}$, $V_{EN}=3.3\text{V}$, $I_{OUT}=0\text{A}$, $T_A=85^\circ\text{C}$		8		nA
		$V_{IN}=5.5\text{V}$, $V_{EN}=5.5\text{V}$, $I_{OUT}=0\text{A}$, $T_A=25^\circ\text{C}$		6	90	nA
		$V_{IN}=5.5\text{V}$, $V_{EN}=5.5\text{V}$, $I_{OUT}=0\text{A}$, $T_A=85^\circ\text{C}$		45		nA
I_{SD}	Shutdown current from IN to GND	$V_{IN}=1.2\text{V}$, $V_{EN}=0\text{V}$, $T_A=25^\circ\text{C}$		7	35	nA
		$V_{IN}=1.8\text{V}$, $V_{EN}=0\text{V}$, $T_A=25^\circ\text{C}$		8	40	nA
		$V_{IN}=3.3\text{V}$, $V_{EN}=0\text{V}$, $T_A=25^\circ\text{C}$		12	90	nA
		$V_{IN}=3.3\text{V}$, $V_{EN}=0\text{V}$, $T_A=85^\circ\text{C}$		1000		nA
		$V_{IN}=4.5\text{V}$, $V_{EN}=0\text{V}$, $T_A=25^\circ\text{C}$		20	130	nA
		$V_{IN}=5.5\text{V}$, $V_{EN}=0\text{V}$, $T_A=25^\circ\text{C}$		45	200	nA
		$V_{IN}=5.5\text{V}$, $V_{EN}=0\text{V}$, $T_A=85^\circ\text{C}$		1650		nA
I_{LEAKEN}	EN pin leakage current	$V_{IN}=0\text{V}$, $V_{EN}=5.5\text{V}$		355	800	nA
R_{EN}	EN pin pull down resistor	$V_{EN}=5.0\text{V}$		15.5		M Ω
POWER SWITCH						
R_{dson}	Internal switch MOSFET on-state resistance	$V_{IN}=5.5\text{V}$, $V_{EN}=\text{high}$, $I_{OUT}=200\text{mA}$, $T_A=25^\circ\text{C}$		24	30	m Ω
		$V_{IN}=3.3\text{V}$, $V_{EN}=\text{high}$, $I_{OUT}=200\text{mA}$, $T_A=25^\circ\text{C}$		29	40	
		$V_{IN}=1.8\text{V}$, $V_{EN}=\text{high}$, $I_{OUT}=200\text{mA}$, $T_A=25^\circ\text{C}$		44	60	
		$V_{IN}=1.2\text{V}$, $V_{EN}=\text{high}$, $I_{OUT}=200\text{mA}$, $T_A=25^\circ\text{C}$		73	90	
t_R	Output rise time	$V_{IN}=3.3\text{V}$, $C_{OUT}=1\mu\text{F}$, $R_{OUT}=5\Omega$		320		μs
t_F	Output fall time	$V_{IN}=3.3\text{V}$, $C_{OUT}=1\mu\text{F}$, $R_{OUT}=5\Omega$		10		μs
t_{ON}	Switch turn on time	$V_{IN}=3.3\text{V}$, $C_{OUT}=1\mu\text{F}$, $R_{OUT}=5\Omega$		360		μs
t_{OFF}	Switch turn off time	$V_{IN}=3.3\text{V}$, $C_{OUT}=1\mu\text{F}$, $R_{OUT}=5\Omega$		5		μs
t_{EN}	Enable time	$V_{IN}=3.3\text{V}$, $C_{OUT}=1\mu\text{F}$, $R_{OUT}=5\Omega$		210		μs
V_{IH}	EN input high threshold level		1.2			V
V_{IL}	EN input low threshold level				0.4	V

Timing Diagram

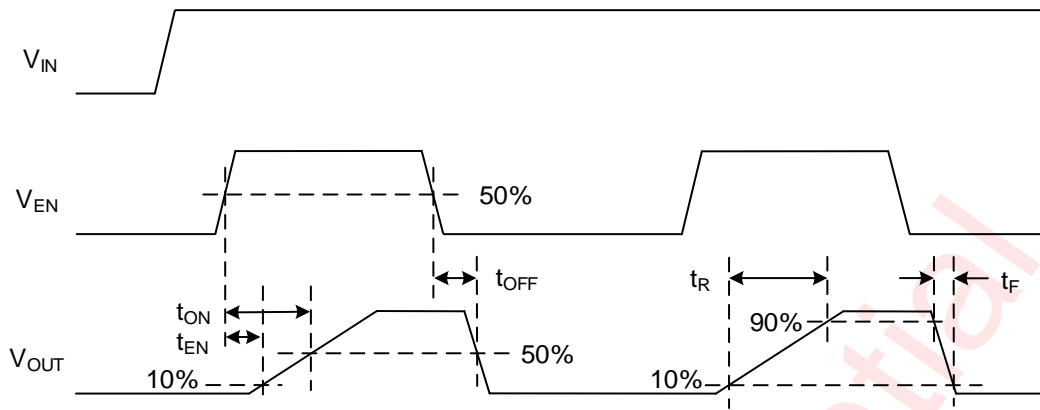


Figure 5 AW35132 Timing Diagram

Typical Characteristics

Ambient temperature is 25°C, $C_{IN} = C_{OUT} = 1\mu F$, unless otherwise noted.

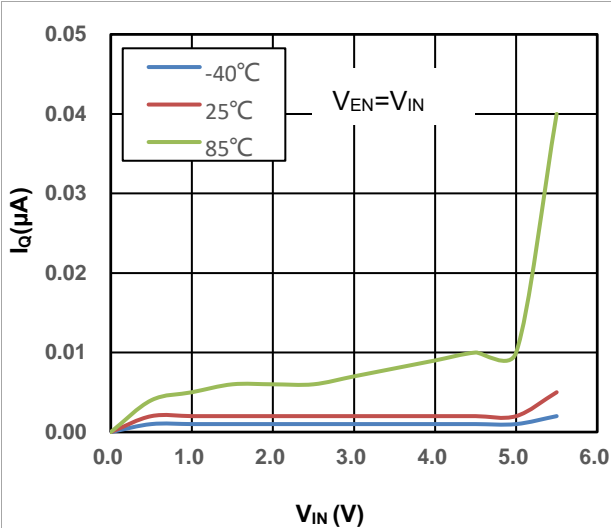


Figure 6 Quiescent Current vs. V_{IN} , No load

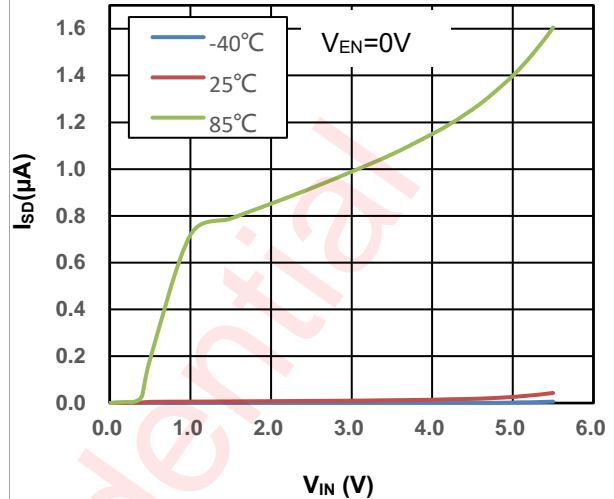


Figure 7 IN Shutdown Current vs. V_{IN}

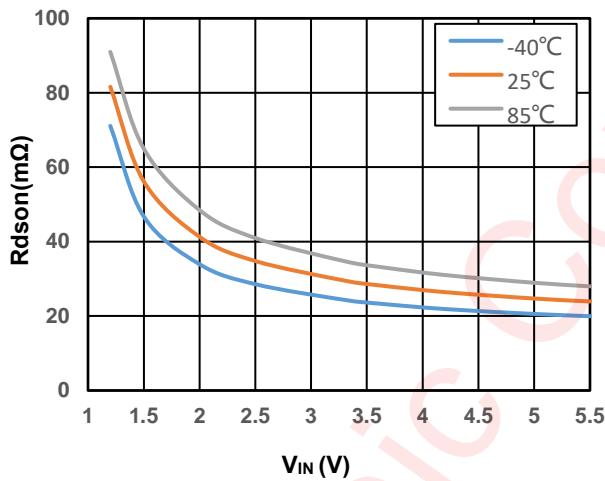


Figure 8 R_{dson} vs. V_{IN} ($I_{OUT} = 200mA$)

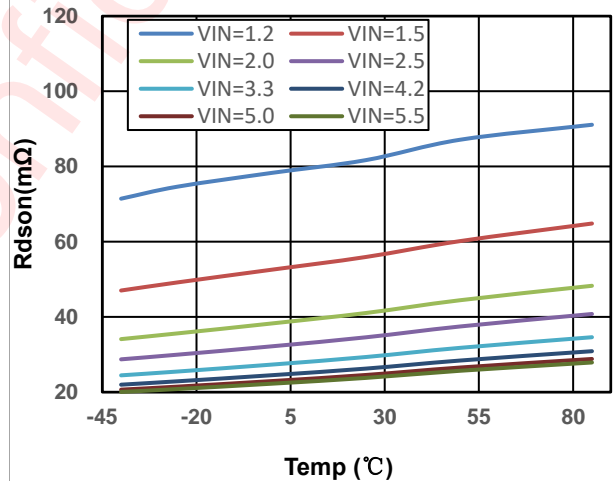


Figure 9 R_{dson} vs. Temperature ($I_{OUT} = 200mA$)

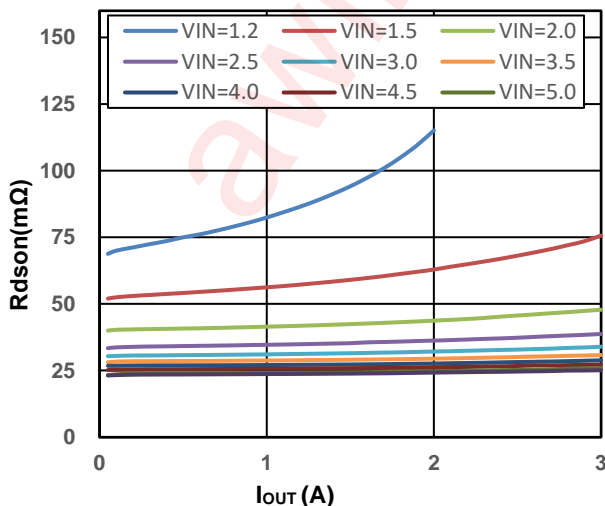


Figure 10 R_{dson} vs. I_{OUT}

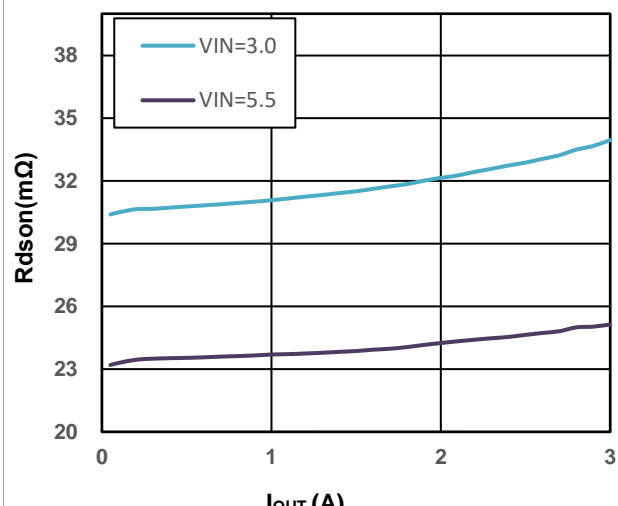


Figure 11 R_{dson} vs. I_{OUT}



C1: 2.00V/div C2: 2.00V/div t=160µs/div
C4: 2.00V/div
VIN=3.3V, CIN=1µF, COUT=1µF, Rload=5Ω

Figure 12 Turn On Response



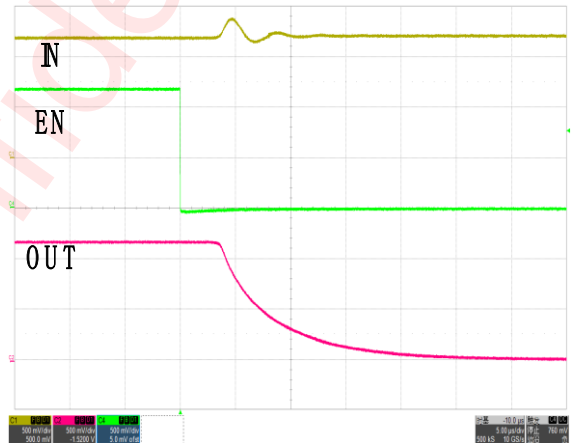
C1: 2.00V/div C2: 2.00V/div t=5µs/div
C4: 2.00V/div
VIN=3.3V, CIN=1µF, COUT=1µF, Rload=5Ω

Figure 13 Turn Off Response



C1: 0.5V/div C2: 0.5V/div t=1.6ms/div
C4: 0.5V/div
VIN=1.2V, CIN=1µF, COUT=1µF, Rload=5Ω

Figure 14 Turn On Response



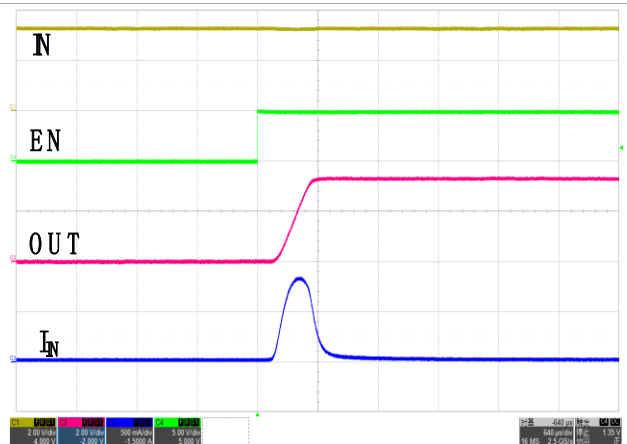
C1: 0.5V/div C2: 0.5V/div t=5µs/div
C4: 0.5V/div
VIN=1.2V, CIN=1µF, COUT=1µF, Rload=5Ω

Figure 15 Turn Off Response



C1: 2.00V/div C2: 2.00V/div t=160µs/div
C4: 2.00V/div
VIN=5.5V, CIN=1µF, COUT=1µF, Rload=5Ω

Figure 16 Turn On Response



C1: 2.00V/div C2: 2.00V/div t=640µs/div
C3: 500mA/div C4: 5.00V/div
VIN=3.3V, CIN=1µF, COUT=100µF, no Rload

Figure 17 Inrush Current with COUT=100µF

Detailed Functional Description

The AW35132 integrates a high side P channel MOSFET load switch, and provides a low on-resistance for a low voltage drop across the device. A controlled slew rate is used in applications to limit the inrush current. The part can be turned on, with a supply voltage from 1.2V to 5.5V.

Turn On/Off Control

Enable pin is an active high. The device is opened when EN pin is tied low (disable) or pulled down by internal 15.5MΩ resistor, forcing PMOS switch off. The IN/OUT path is activated with a minimum of V_{in} of 1.2V and EN forced to high level.

Table 1. Functional Table

EN	IN to OUT	OUT to GND
Low	OFF	OFF
High	ON	OFF

Slew Rate Control

When the switch is enabled, the device regulates the gate voltage of MOSFET, and controls the V_{OUT} slew rate during t_R to avoid a large input inrush current. The feature reduces the interference to the power supply.

PCB Layout Consideration

AW35132 is a low ON-Resistance load switch, to obtain the optimal performance, PCB layout should be considered carefully. Here are some guidelines:

1. All the peripherals should be placed as close to the device as possible. Place the input capacitor C_{IN} on the top layer (same layer as the AW35132) and close to IN pin, and place the output capacitor C_{OUT} on the top layer (same layer as the AW35132) and close to OUT pin.
2. The AW35132 integrate an up to 3A rated PMOS FET, and the PCB design rules must be respected to properly evacuate the heat out of the silicon. By increasing PCB area, especially around IN and OUT pins, the $R_{\theta JA}$ of the package can be decreased, allowing higher power dissipation. Red bold paths on Figure 18 are power lines that will flow large current, please route them on PCB as straight, wide and short as possible.
3. Use rounded corners on the power trace from the power supply connector to AW35132 to decrease EMI coupling.

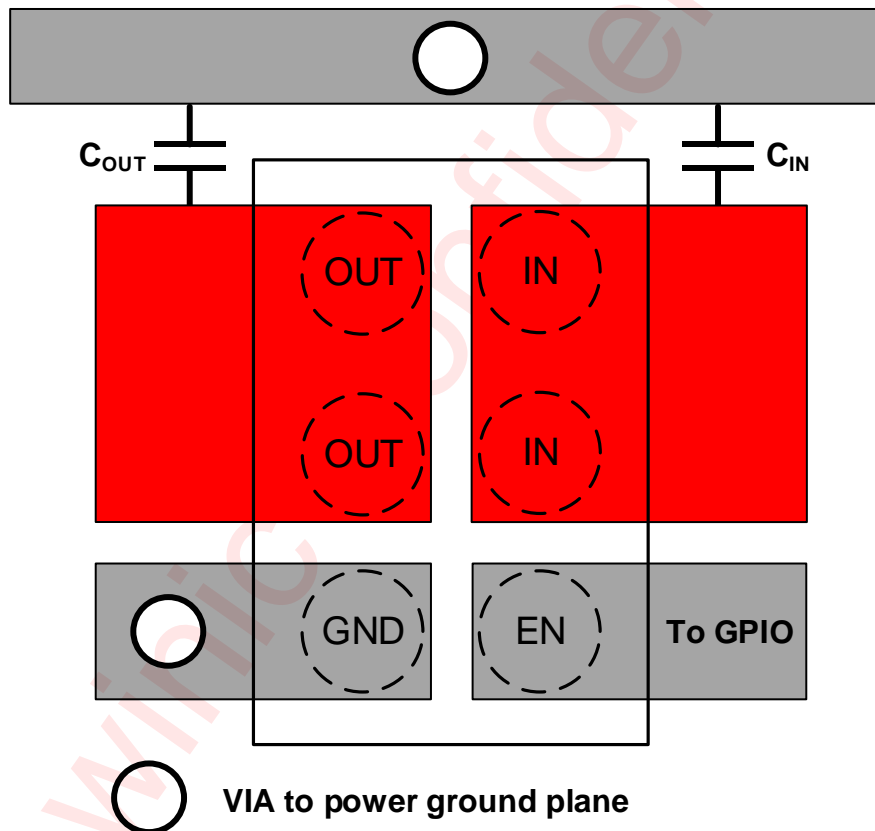
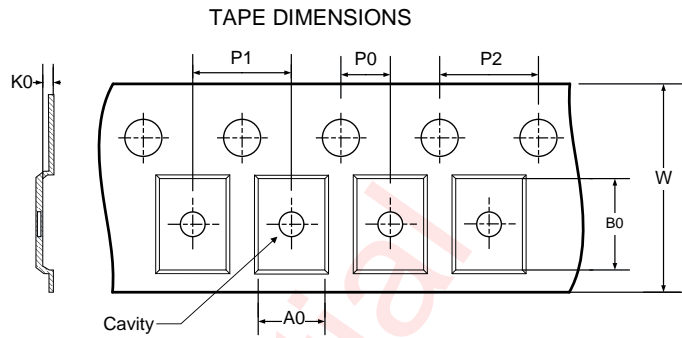
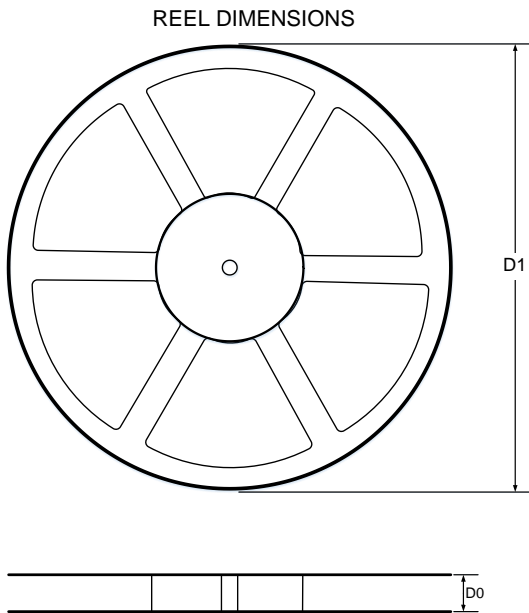


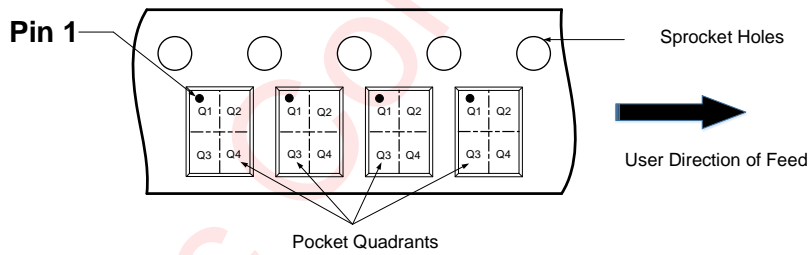
Figure 18 PCB layout example

Tape And Reel Information



- A0: Dimension designed to accommodate the component width
- B0: Dimension designed to accommodate the component length
- K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P0: Pitch between successive cavity centers and sprocket hole
- P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
- D1: Reel Diameter
- D0: Reel Width

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

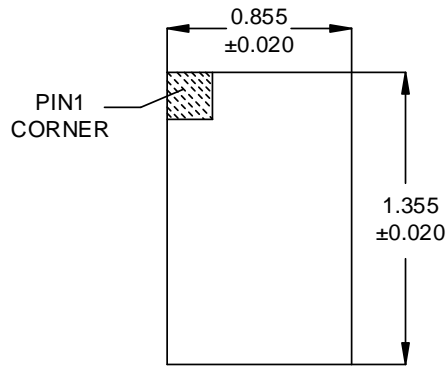


DIMENSIONS AND PIN1 ORIENTATION

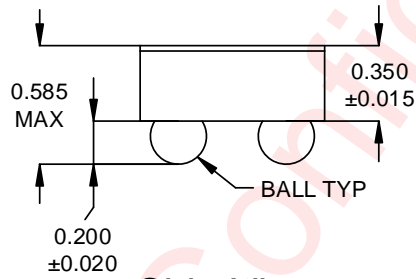
D1 (mm)	D0 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
179.00	9.00	0.95	1.45	0.65	2.00	4.00	4.00	8.00	Q1

All dimensions are nominal

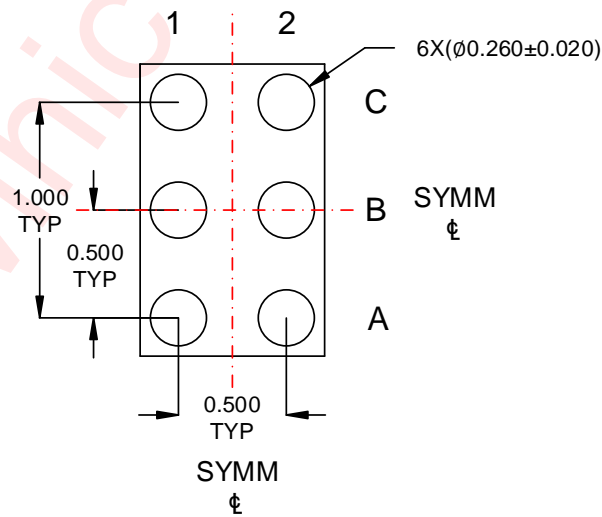
Package Description



Top View



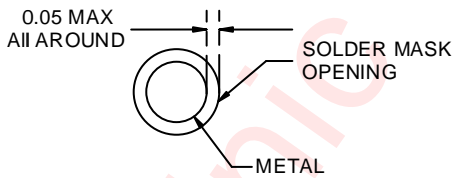
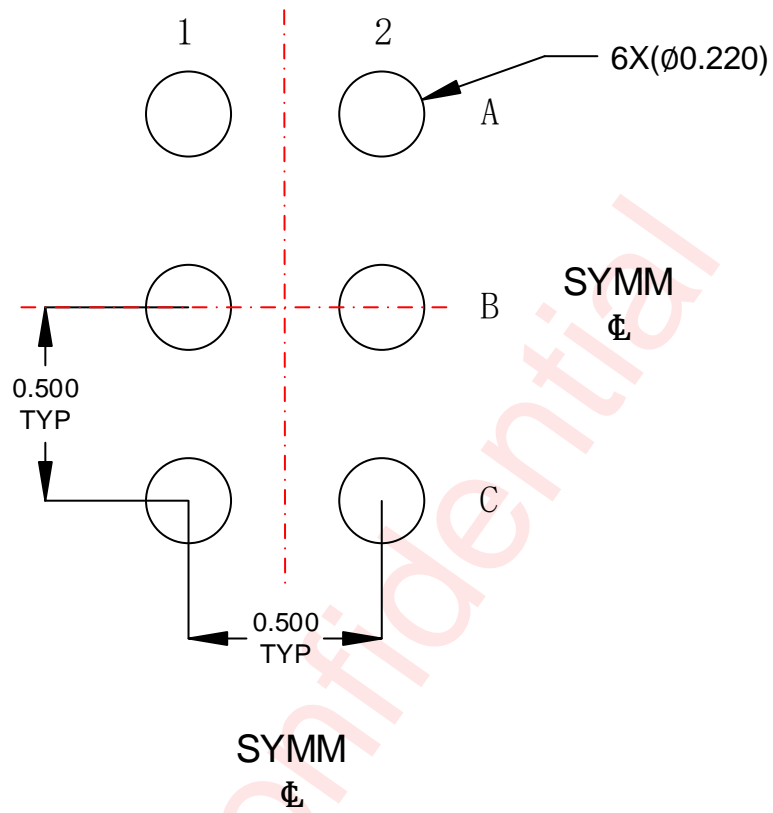
Side View



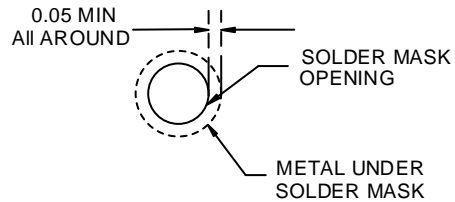
Bottom View

Unit: mm

Land Pattern Data



NON-SOLDER MASK DEFINED



SOLDER MASK DEFINED

Unit: mm

Revision History

Version	Date	Change Record
V1.0	October 2020	Datasheet V1.0 Released

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